

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Lopatin, *et al.*
Title: METHOD OF USING TERNARY COPPER
ALLOY TO OBTAIN A LOW RESISTANCE
AND LARGE GRAIN SIZE INTERCONNECT
Appl. No.: 09/994,395
Filing Date: 11/26/2001
Examiner: Ori Nadav
Art Unit: 2811
Confirmation Number: 7882

REPLY UNDER 37 CFR 1.116

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Final Office Action dated July 12, 2007, concerning the above-referenced patent application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this document.

Remarks/Arguments begin on page 6 of this document.

OK to enter

O.N. 8/9/07